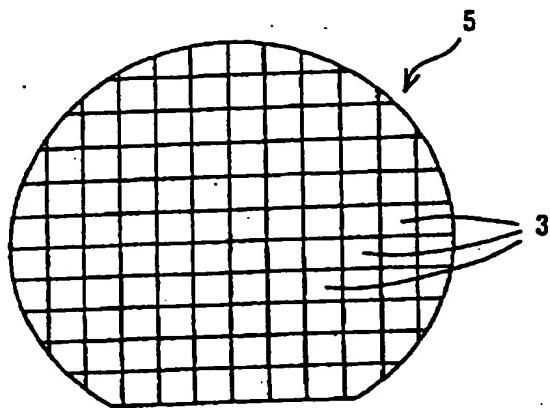
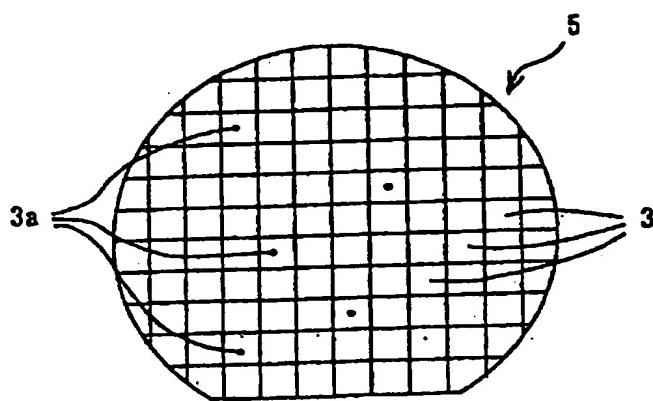


**Fig. 1**



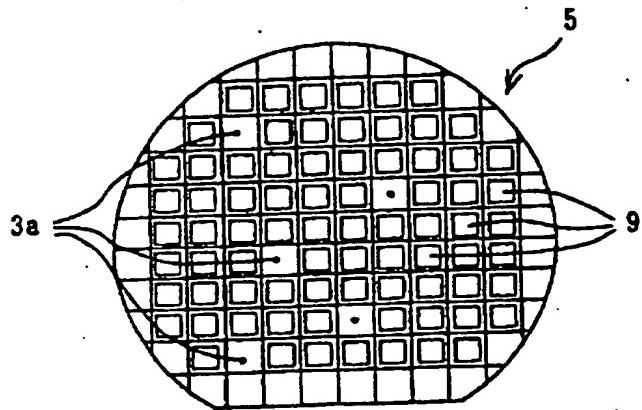
**3: Semiconductor chip forming section**  
**5: Semiconductor wafer**

**Fig. 2**



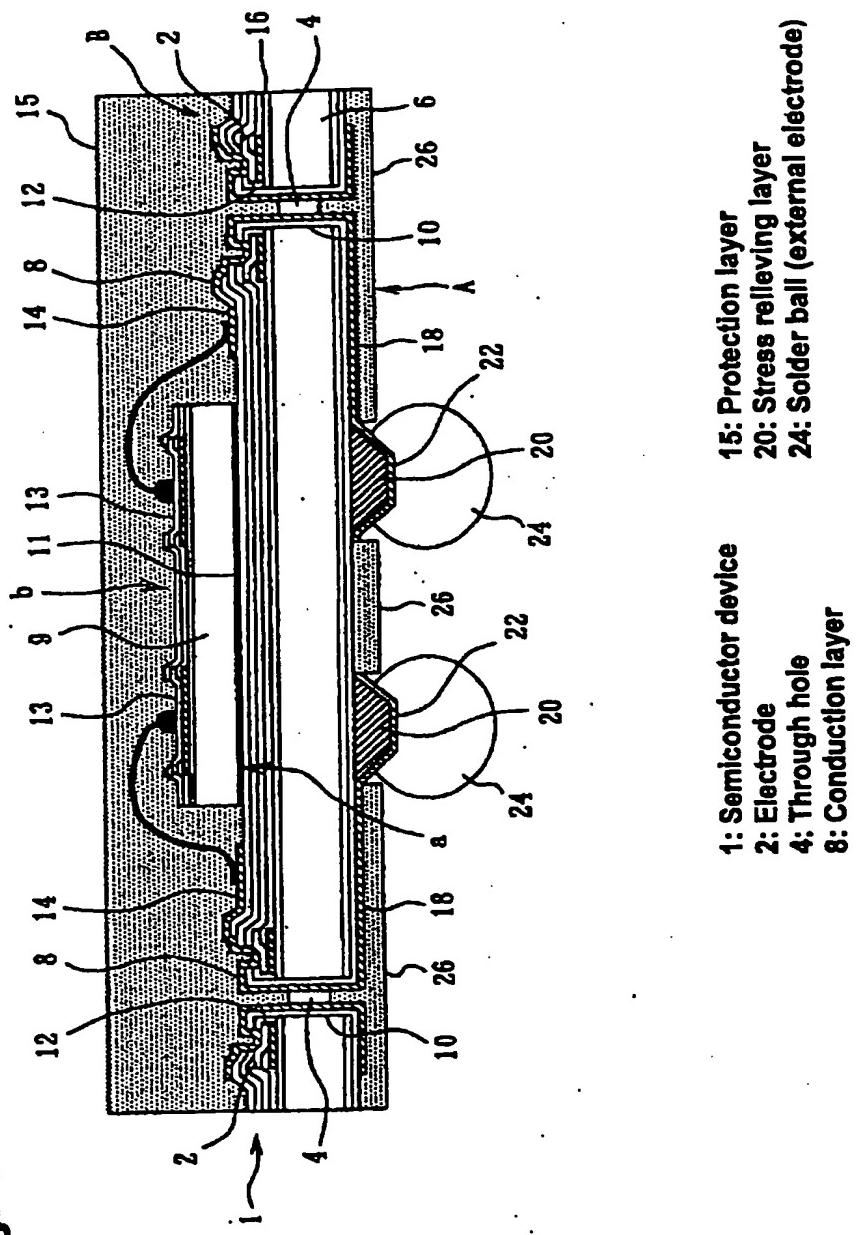
**3a: "BAD" mark**

**Fig. 3**



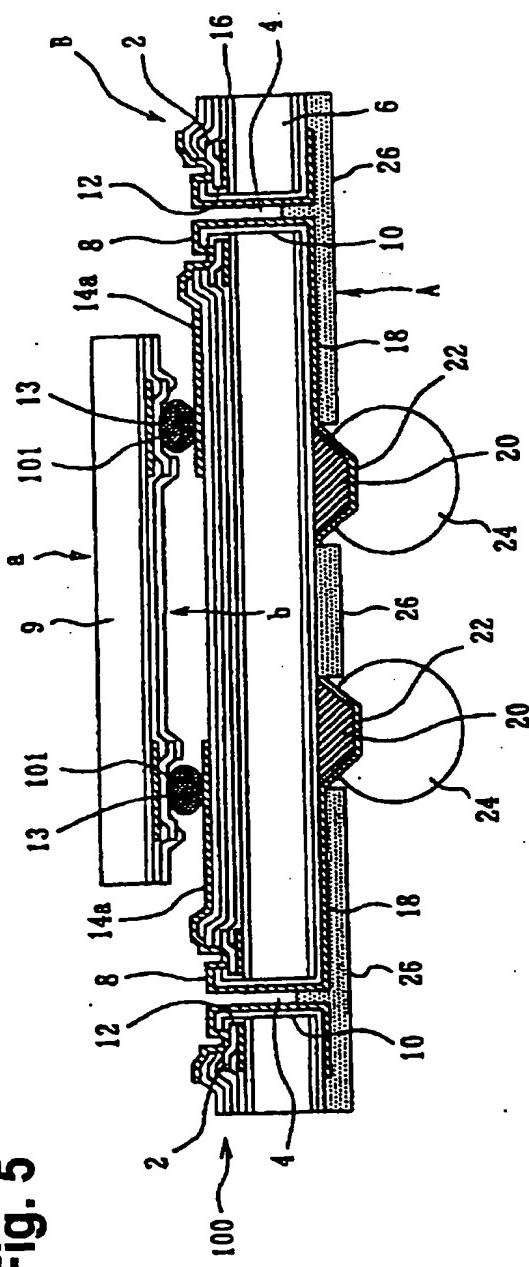
**9: Segmented other semiconductor chips**

**Fig. 4**



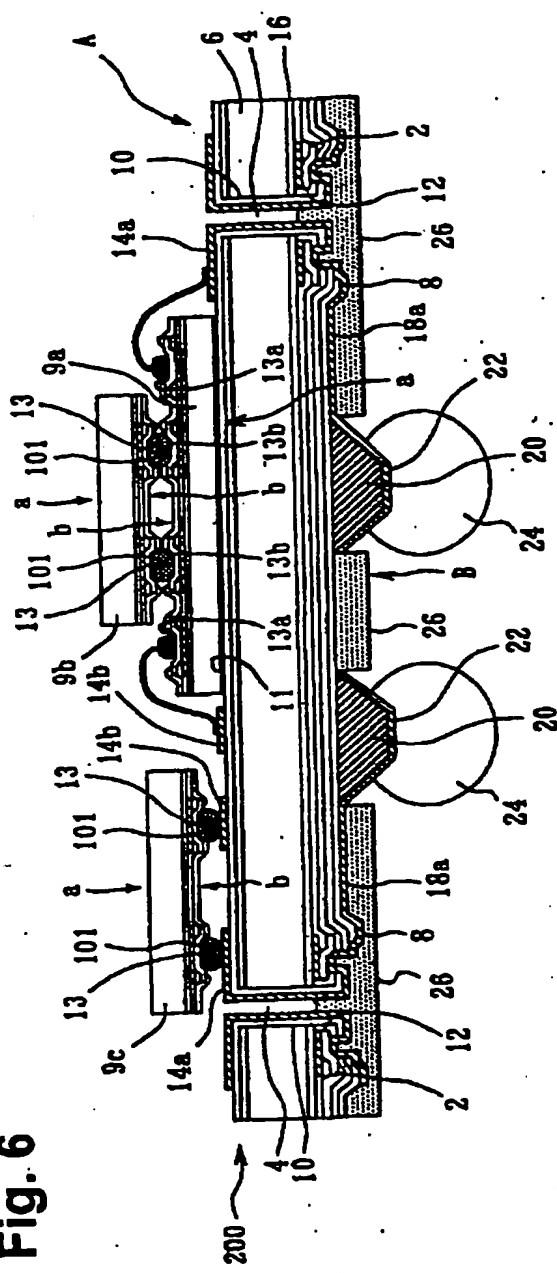
- 1: Semiconductor device
- 2: Electrode
- 4: Through hole
- 8: Conduction layer
- 15: Protection layer
- 20: Stress relieving layer
- 22, 24, 26: Solder ball (external ball)

**Fig. 5**



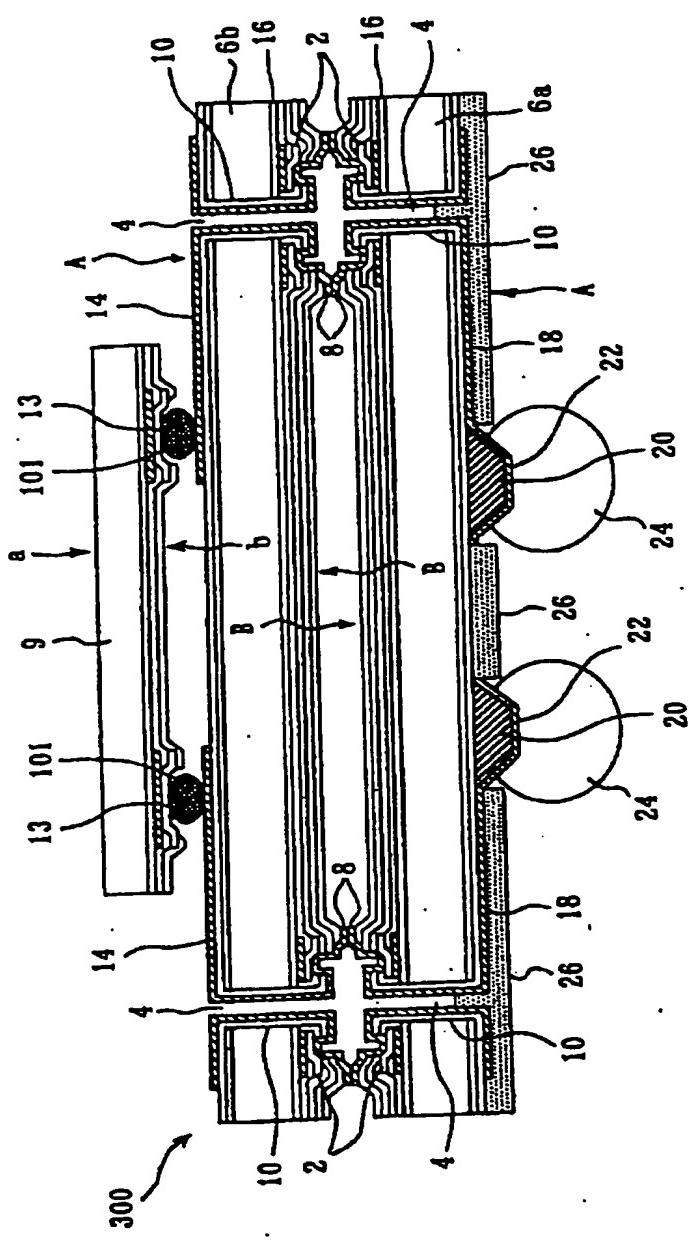
**100: Semiconductor device**

Fig. 6



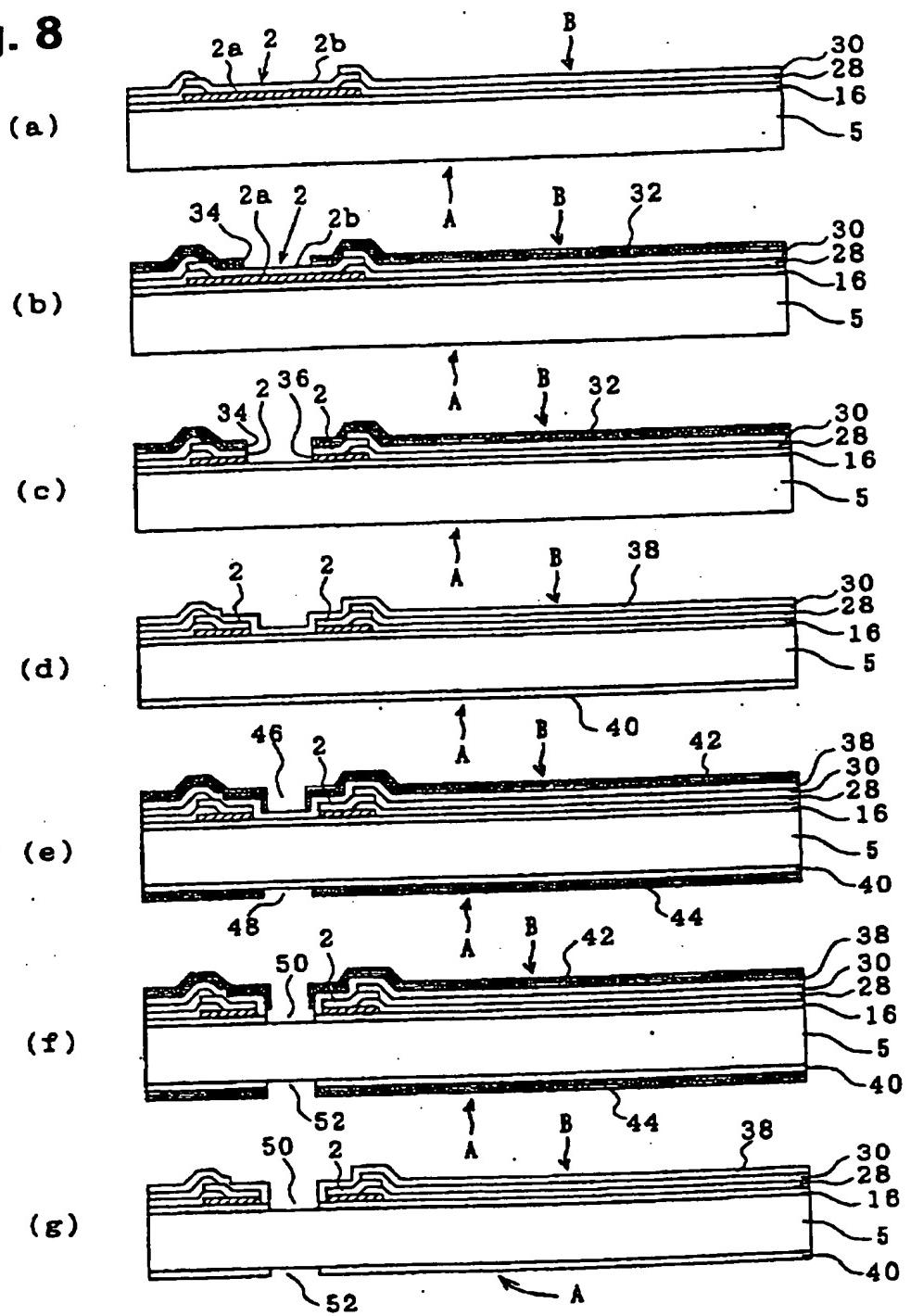
**9a, 9b, 9c : Segmented other semiconductor chips  
200 : Semiconductor device**

**Fig. 7**

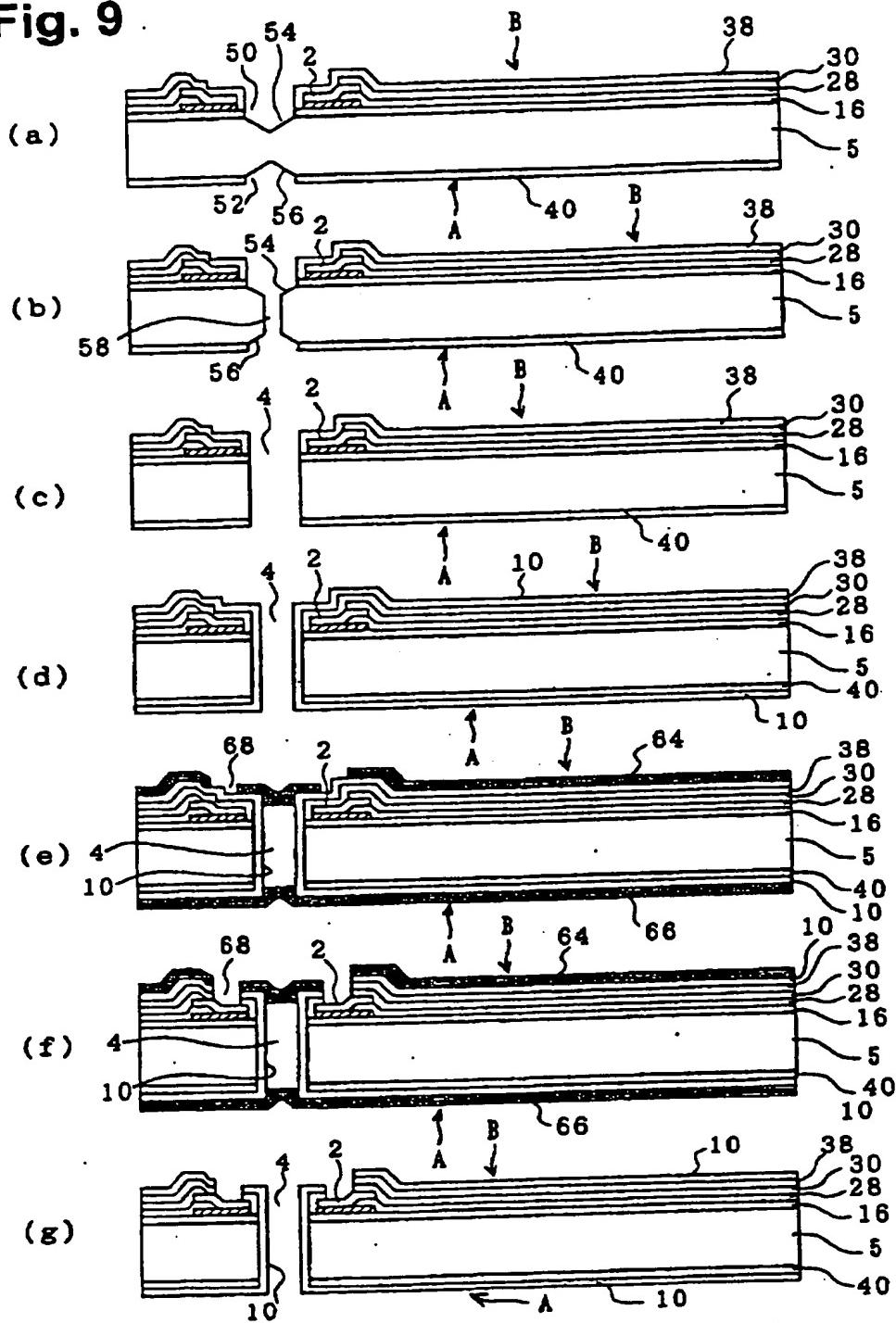


**6b: Segmented another semiconductor chip  
300 : Semiconductor device**

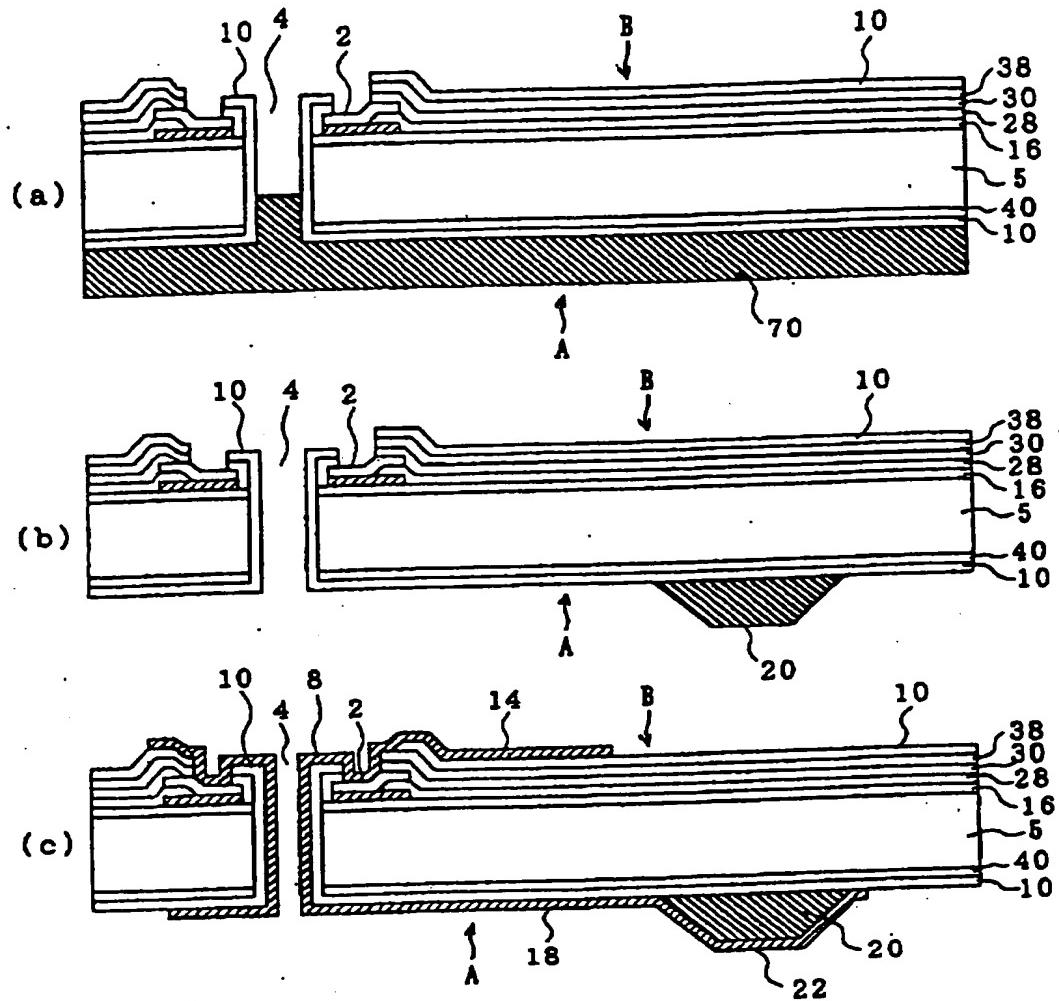
**Fig. 8**



**Fig. 9**



**Fig. 10**



**Fig. 11**

